

Measurement of the Surface Recombination Velocity S at the Si-SiO₂ Interface by the Dual-Mercury Probe Method

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A novel measurement technique of the surface recombination velocity S at the Si-SiO₂ interface by the dual-mercury probe method is proposed. It is shown that the S experimentally obtained has the pyramid-like peak from near flat-band to midgap condition and takes an extremely low value less than 10 cm/s at both inversion and accumulation condition. In addition, the S is compared with the interface-state density D_{it} .

1. Introduction

The thermally grown Si-SiO₂ interface is the essential material system for many Si devices. Numerous characterization techniques for the interface are generally concerned with the measurement of the majority-carrier properties¹⁾. For minority-carrier devices such as a solar cell, it is important, however, to understand the properties of minority carriers, e.g., electron-hole recombination at the interface. The recombination is usually characterized by a surface recombination velocity S , that corresponds to a minority-carrier lifetime τ in the Si bulk. The S expressed by the Shockley-Read-Hall (SRH) statistic is a complex function of Si-SiO₂ interface properties, i.e., the density and capture cross section of Si-SiO₂ interface states, and surface carrier densities²⁾. Therefore, a technique to experimentally determine the S must be required. To our knowledges, very few works have been reported so far³⁾⁻⁴⁾.

In this paper, a novel measurement technique of the S at the Si-SiO₂ interface based on the dual-mercury probe method^{5), 6)} is

described. It is shown that the S at different Si-SiO₂ interfaces is successfully evaluated as a function of a gate bias voltage. The experimental results are investigated, comparing with the interface-state density D_{it} .

2. Experimental and analytical method

2.1 Measurement setup and samples

The measurement setup for the evaluation of S is schematically shown in Fig.1. Two mercury probes (0.5mm ϕ , space:5mm) made contacts with the HF-etched back surface of the oxidized Si wafer sample through a Mylar orifice plate by vacuum-pumping through a little gap between the Mylar plate and the wafer.

The measured samples were n-type, (100)-oriented, 17-22 Ω -cm, FZ Si wafers, oxidized in dry O₂ (SiO₂~800Å) and followed by evaporation of Indium Tin Oxide (ITO) films as transparent gates. One sample was annealed in O₂ at 800°C for 30min before the ITO evaporation. Another sample was annealed in H₂ at 400°C for 30min after the dry O₂ oxidation and ITO evaporation to reduce the

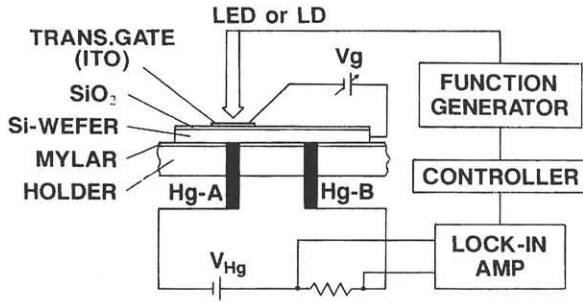


Fig.1 Schematic measurement setup for the dual-mercury probe method for the evaluation of the surface recombination velocity S at the Si-SiO₂ interface.

Si-SiO₂ interface-state density.

The intensity-modulated light (GaAs LED: 3mW) illuminated the ITO gate to generate minority carriers near the Si-SiO₂ interface. One Hg probe situated beneath the ITO gate was reversely biased to collect a part of photo-generated minority carriers diffused from the vicinity of the Si-SiO₂ interface. A gate voltage was applied to change surface band bending. The DC bias light of a W-lamp (50 mW/cm²) also illuminated the whole front surface of the sample to reduce the resistance of the measurement circuit. The frequency-dependent photocurrent was measured as a function of gate bias voltage by using a 100kHz lock-in amplifier. To determine the τ and D of the sample, the similar measurement of the photocurrent was also performed at the sandblasted surface. The interface-state density D_{it} of each sample was estimated by the quasi-static and high-frequency C-V measurement.

2.2 Evaluation procedures of the surface recombination velocity S

The evaluation of the τ and D of minority carriers in the Si wafer using the dual-mercury probe method has been presented previously in detail⁵⁾ and will therefore only be reviewed here. The behavior of the photo-generated minority carriers is ap-

proximately dealt with to be one-dimensional for brevity. Because the applied DC bias appears mainly in the depletion region of the reversely biased Hg contact. In such a case, the photocurrent picked up by the Hg contact is expressed as a solution of continuity and diffusion equations with adequate boundary conditions⁷⁾ and is a complicated function with three unknown parameters, τ , D , and S . One way to simplify the analytical solution is to eliminate one of these parameters. It has been shown that, for S higher than around 10⁶ cm/s, the normalized photocurrent is independent on the value of S ⁵⁾. We adopt this limited case for the evaluation of τ and D by measuring the sandblasted surface of the wafer sample. For the case of $W/L > 3$ and $\omega\tau \gg 1$, where $L = \sqrt{\tau D}$ and ω is an angular frequency, τ and D have been shown to be able to be graphically determined from the simplified analytical formula⁵⁾. However, even for the other cases, we can obtain τ and D by curve-fitting with the aid of calculated correction factors. After the determination of τ and D , the dependence of the photocurrent on S can be calculated as a function of modulation frequency. Then the S at given surface on the wafer sample can be evaluated by comparing the experimental data with the corresponding calculations. In other words, the proposed technique makes it possible to determine τ and S separately. The accuracy of the determined S is generally improved for a wafer sample with longer minority-carrier lifetime and/or larger thickness. The above-mentioned procedures were used for the evaluation of the S at the Si-SiO₂ interfaces as a function of the gate bias voltage.

The energy distribution of the Si-SiO₂ interface-state density D_{it} was measured by a conventional quasi-static and high-frequency C-V method to compare it with the experimentally obtained S .

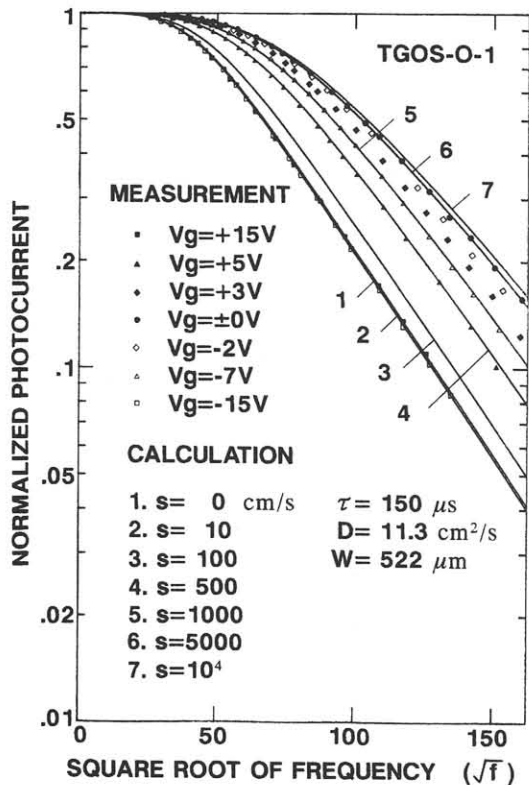


Fig. 2 Dependence of the surface recombination velocity S on gate bias voltage at the Si-SiO₂ interface annealed in O₂ at 800°C for 30min after the dry O₂ oxidation. The gates were transparent ITO films.

3. Experimental results and discussions

Figure 2 shows the experimental results of the log(normalized photocurrent) vs. square root of frequency (\sqrt{f}) characteristics for the Si-SiO₂ sample annealed in O₂. For the calculation shown by solid curves in Fig. 2, the experimentally evaluated τ of 150 μ s, D of 11.3 cm²/s, and W of 522 μ m were used. The dependence of the surface recombination velocity S on gate bias voltage was then determined and is plotted in Fig. 3 for both samples. For the O₂-annealed sample, it is obvious from Figs. 2 and 3 that the S of photo-generated minority carriers is less effective under both accumulation and inversion conditions due to lack of either majority or minority carriers at the Si-SiO₂ interface, which is in good agreement with the theoretical works^{3), 4), 8)}. This experimental

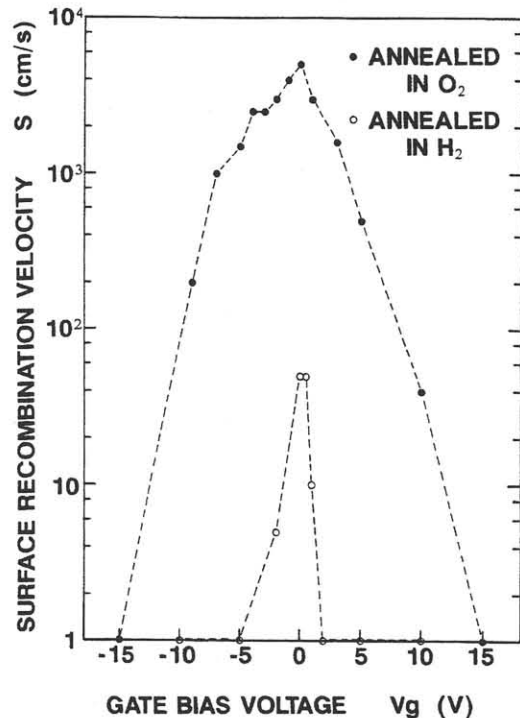


Fig. 3 Dependence of the surface recombination velocity S on gate bias voltage at the Si-SiO₂ interface annealed in O₂ at 800°C for 30 min after the dry O₂ oxidation (●), and the Si-SiO₂ interface annealed in H₂ at 400°C for 30 min after the dry O₂ oxidation and the ITO evaporation (○). The limit of the determination of S is about 1 cm/s.

result means that strong band bending at the semiconductor surface is quite effective to reduce the carrier recombination whether high $D_{1\tau}$ exists or not, and is suggestive for realization of a high efficiency solar cell. The broad peak of S for the sample annealed in O₂ may be due to a high level injection condition. Under moderate band bending or flatband condition, the S depends on $D_{1\tau}$ and capture cross sections, σ_p and σ_n of the interface states. The $D_{1\tau}$ determined by the quasi-static (sweep rate: 0.02V/s) and high-frequency (100kHz) C-V measurement are plotted in Fig. 4, which indicates nearly constant and high level value within the measurement for the O₂-annealed sample. At near midgap region, a high level injection condition of $n_s = p_s \gg n_1$ was fulfilled. In that case, the experimentally obtainable S is

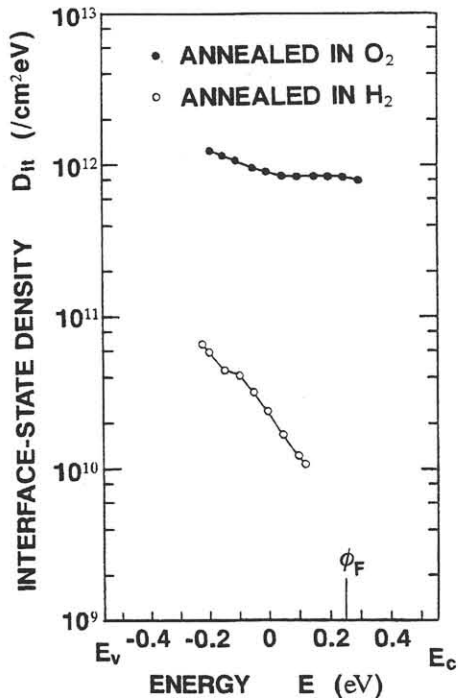


Fig.4 Interface-state density D_{it} as a function of energy for the O_2 -annealed sample (\bullet), and the H_2 -annealed sample (\circ). D_{it} was determined by the quasi-static and high frequency C-V measurement.

expressed as $v_{th}\{\sigma_p\sigma_n/(\sigma_p+\sigma_n)\}$ (integral of D_{it} with energy), where v_{th} is the average thermal velocity of carriers. By using this relation and the experimental data for the O_2 -annealed sample in Figs.3 and 4, the smaller capture cross section is estimated to be $5-7 \times 10^{-16} \text{ cm}^2$. It has been reported that σ_p is smaller than σ_n ³⁾. Therefore the obtained capture cross section is considered for holes. However the data for the O_2 -annealed sample in Fig.3 show the high value of S even near flatband condition, which means whether σ_p still has the order of 10^{-16} cm^2 in upper bandgap and/or σ_n takes the order of 10^{-16} cm^2 . It must be said, therefore, that more works for various samples are necessary. For the H_2 -annealed sample, the peak value of S is suppressed less than 50 cm/s as experimentally shown in Fig.3. This satisfactorily corresponds to the fact that the D_{it} indicates 1.5-2 order less than for the O_2 -annealed sample as shown

in Fig.4. The situation of the quite low S under accumulation and inversion condition is the same as for the sample annealed in O_2 . It is apparent that a well-prepared Si-SiO₂ interface is also effective to reduce the surface carrier recombination.

4. Conclusion

The novel measurement technique of the surface recombination velocity S at the Si-SiO₂ interface based on the dual-mercury probe method has been proposed. The S for the Si-SiO₂ interfaces with different D_{it} has successfully been evaluated as a function of gate bias voltage. For each sample, the quite low S under accumulation and inversion condition and the D_{it} -dependent pyramid-like peak of S from midgap to flatband condition have been observed. The information obtainable by the proposed technique is quite useful for many minority-carrier devices, especially for solar cell design.

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